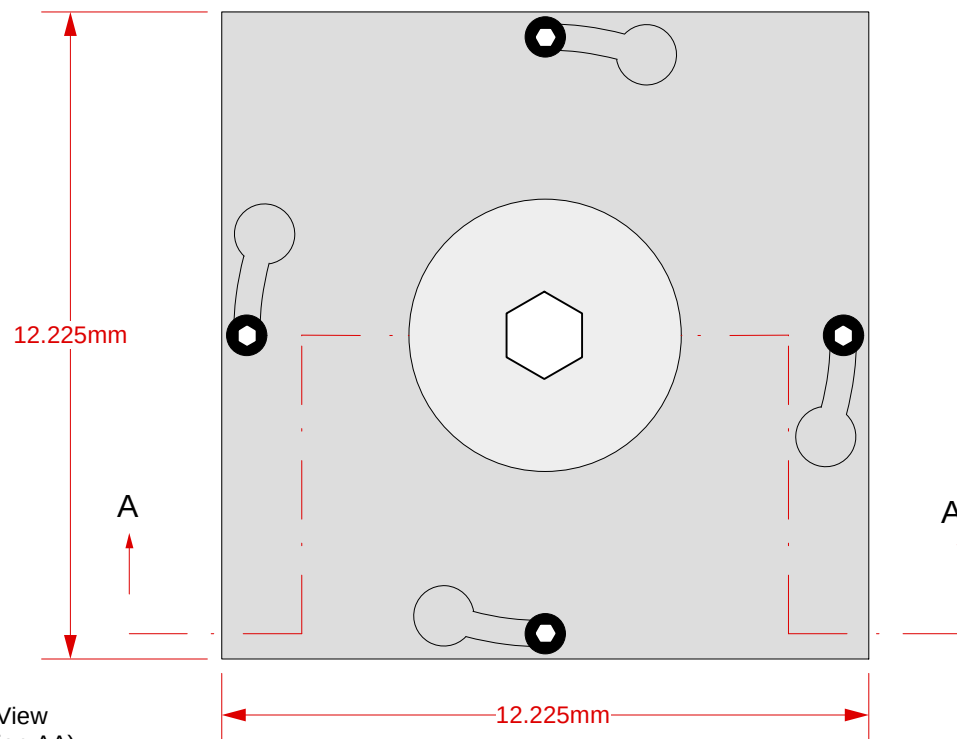
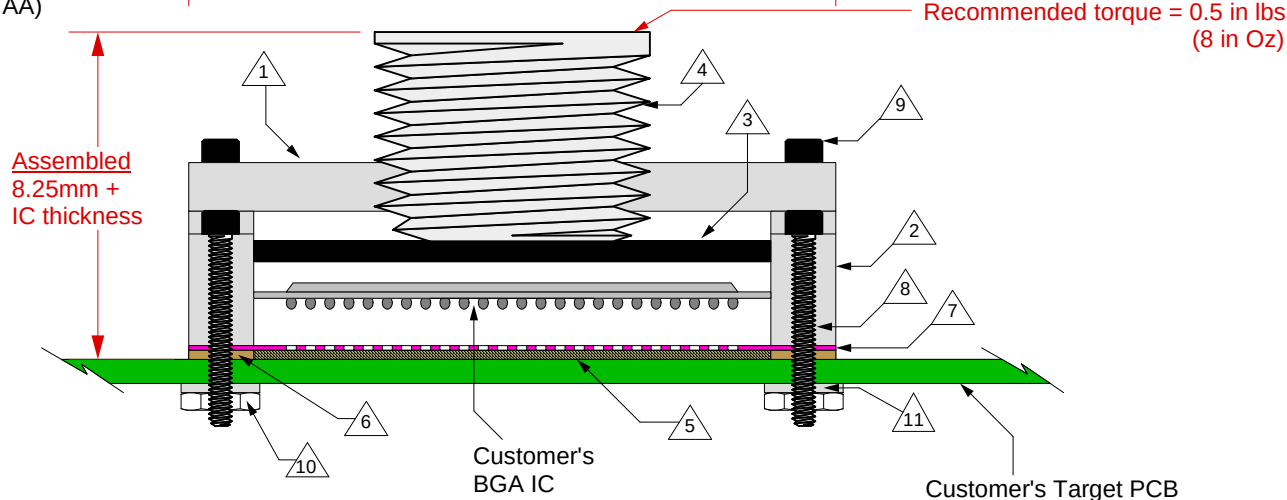


Top View



Side View
(Section AA)



GHz BGA Socket - Direct mount, solderless

Features

- Directly mounts to target PCB (needs tooling holes) with hardware.
- High speed, reliable Elastomer connection
- Minimum real estate required
- Compression plate distributes forces evenly
- Ball guide prevents over compression of elastomer
- Easily removable swivel socket lid

- Socket Lid: Black anodized Aluminum. Thickness = 2.5mm.
- Socket base: Black anodized Aluminum. Thickness = 5mm.
- Compression Plate: Black anodized Aluminum. Thickness = 2.5mm.
- Compression screw: Clear anodized Aluminum. Thickness = 5mm, Hex socket = 5mm.
- Elastomer: 40 micron dia gold plated brass filaments arranged symmetrically in a silicone rubber (63.5 degree angle). Thickness = 0.75mm.
- Elastomer Guide: Non-clad FR4. Thickness = 0.725mm.
- Ball Guide: Kapton polyimide.
- Socket base screw: Socket head cap, Alloy steel with black oxide finish, 0-80 fine thread, 9.525mm long.
- Socket lid screw: Shoulder screw, 18-8 SS, 0-80 fine thread.
- Socket base nut: 18-8 Stainless steel, 0-80 fine thread.
- Nylon washer: 1.73mm ID; 4.78mm OD 0.64mm thickness.

SG-BGA-6018 Drawing

Status: Released

Scale: -

Rev: G



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Drawing: E Smolentseva

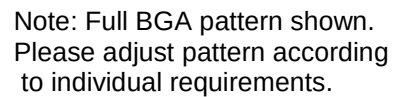
File: SG-BGA-6018 Dwg.mcd

Date: 9/6/01

Modified: 6/26/09, AE

All tolerances: ± 0.125 mm (unless stated otherwise). Materials and specifications are subject to change without notice.

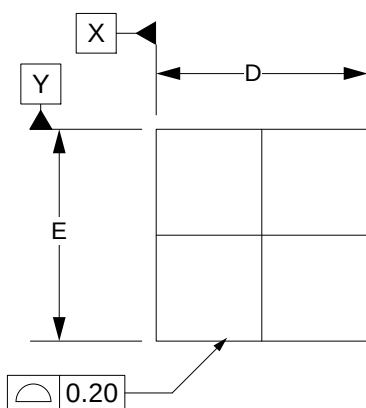
***Note: BGA pattern is not symmetrical with respect to the mounting holes.**



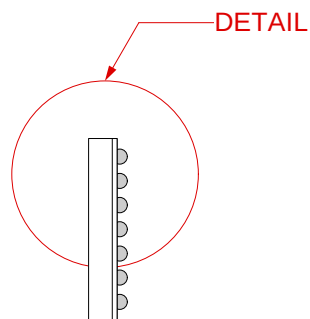
Total thickness: 1.6mm min.
Plating: Gold or Solder finish
PCB Pad height: Same or higher than solder mask

Recommended PCB Layout Tolerances: $\pm 0.025\text{mm}$ [$\pm 0.001"$] unless stated otherwise.

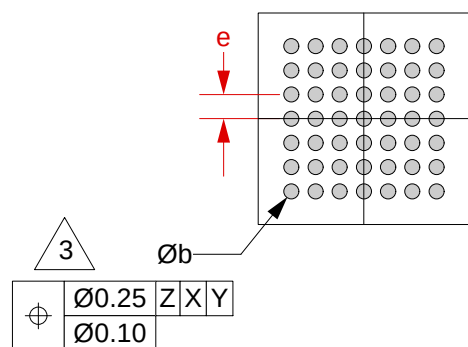
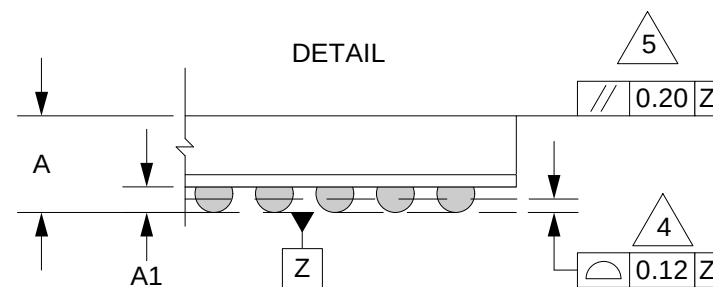
PAGE 2 of 3



TOP VIEW



SIDE VIEW



BOTTOM VIEW

- 1 Dimensions are in millimeters.
- 2 Interpret dimensions and tolerances per ASME Y14.5M-1994.
- 3 Dimension b is measured at the maximum solder ball diameter, parallel to datum plane Z.
- 4 Datum Z (seating plane) is defined by the spherical crowns of the solder balls.
- 5 Parallelism measurement shall exclude any effect of mark on top surface of package.

DIM	MIN	MAX
A		2.5
A1	0.25	0.4
b		0.55
D	7.00 BSC	
E	7.00 BSC	
e	0.80 BSC	

Array 7x7

SG-BGA-6018 Drawing		Status: Released	Scale: -	Rev: G
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	File: SG-BGA-6018 Dwg.mcd		Modified: 6/26/09, AE	